

Vishay Siliconix

Automotive Dual P-Channel 60 V (D-S) 175 °C MOSFET



PRODUCT SUMMARY					
V _{DS} (V)	-60				
$R_{DS(on)}(\Omega)$ at $V_{GS} = -10 \text{ V}$	0.0480				
$R_{DS(on)}(\Omega)$ at $V_{GS} = -4.5 \text{ V}$	0.0612				
I _D (A) per leg	-8				
Configuration	Dual				

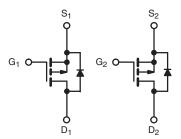
FEATURES

- TrenchFET® power MOSFET
- AEC-Q101 qualified
- 100 % Rg and UIS tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912





ROHS COMPLIANT HALOGEN FREE



P-Channel MOSFET P-Channel MOSFET

ORDERING INFORMATION	
Package	SO-8
Lead (Pb)-free and halogen-free	SQ4917CEY (for detailed order number please see www.vishay.com/doc?79771)

PARAMETER	, , , , , , , , , , , , , , , , , , , ,	SYMBOL	LIMIT	UNIT
Drain-source voltage		V _{DS}	-60	
Gate-source voltage		V _{GS}	± 20	V
Continuous drain current	T _C = 25 °C	- I _D	-8	
	T _C = 125 °C		-4.75	
Continuous source current (diode conduction)		I _S	-4.5	А
Pulsed drain current a		I _{DM}	-32	
Single pulse avalanche current	0.4	I _{AS}	-22.4	
Single pulse avalanche energy	L = 0.1 mH	E _{AS}	25	mJ
Maximum power dissipation	T _C = 25 °C	D	5	\A/
	T _C = 125 °C	P_{D}	1.67	W
Operating junction and storage temperature range		T _J , T _{stq}	-55 to +175	°C

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	LIMIT	UNIT	
Junction-to-ambient	PCB mount b	R_{thJA}	110	°C/W	
Junction-to-foot (drain)		R_{thJF}	30	C/VV	

Notes

- a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %
- b. When mounted on 1" square PCB (FR-4 material)



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PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static	*	•			•		
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$		-60	-	-	V
Gate-source threshold voltage	V _{GS(th)}	V _{DS} =	$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$		-2.0	-2.5	ľ
Gate-source leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA
Zero gate voltage drain current		$V_{GS} = 0 V$	V V _{DS} = -60 V -		-	-1	
	I _{DSS}	V _{GS} = 0 V	V _{DS} = -60 V, T _J = 125 °C	-	-	-50	μΑ
		V _{GS} = 0 V	V _{DS} = -60 V, T _J = 175 °C	-	-	-150	
On-state drain current ^a	I _{D(on)}	V _{GS} = -10 V	V _{DS} ≤ -5 V	-30	-	-	Α
	. ,	V _{GS} = -10 V	I _D = -4.3 A	_	0.0421	0.0480	Ω
	_	V _{GS} = -10 V	I _D = -4.3 A, T _J = 125 °C	-	_	0.0780	
Drain-source on-state resistance a	R _{DS(on)}		I _D = -4.3 A, T _J = 175 °C	_	-	0.0960	
		V _{GS} = -4.5 V	I _D = -3.8 A	_	0.0566	0.0612	
Forward transconductance b	9 _{fs}	V _{DS} =	= -15 V, I _D = -4.3 A	-	12	-	S
Dynamic ^b					l		
Input capacitance	C _{iss}			_	1575	1910	
Output capacitance	C _{oss}	V _{GS} = 0 V	V _{DS} = -30 V, f = 1 MHz	_	175	417	pF
Reverse transfer capacitance	C _{rss}			-	113	142	
Total gate charge ^c	Qg			-	36.3	65	
Gate-source charge c	Q _{gs}	V _{GS} = -10 V	$V_{DS} = -30 \text{ V}, I_{D} = -5 \text{ A}$	_	5.3	-	nC
Gate-drain charge ^c	Q _{gd}			_	8.9	-	
Gate resistance	R _g		f = 1 MHz		2.36	4	Ω
Turn-on delay time ^c	t _{d(on)}			-	11	17	
Rise time ^c	t _r	- V	V 20 V D 20 C		5	17	- ns
Turn-off delay time ^c	t _{d(off)}	$V_{DD} = -30 \text{ V}, \text{ R}_L = 8.8 \Omega$ $I_D \cong -5 \text{ A}, \text{ V}_{GEN} = -10 \text{ V}, \text{ R}_g = 1 \Omega$		-	32	52	
Fall time ^c	t _f			-	5	9	
Source-Drain Diode Ratings and Charact	eristics b				<u> </u>		
Pulsed current ^a	I _{SM}			-	-	-32	Α
Forward voltage	V _{SD}	I _F = -2.8 A, V _{GS} = 0 V		-	-0.79	-1.2	V
Body diode reverse recovery time	t _{rr}	I _F = -2.5 A, di/dt = 100 A/μs		-	29	58	ns
Body diode reverse recovery charge	Q _{rr}			-	44	88	nC
Reverse recovery fall time	t _a			-	24	-	ns
Reverse recovery rise time	t _b			-	5	-	

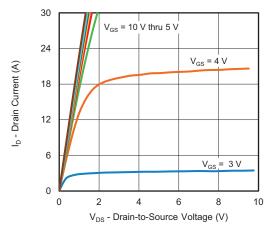
Notes

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%$
- b. Guaranteed by design, not subject to production testing
- c. Independent of operating temperature

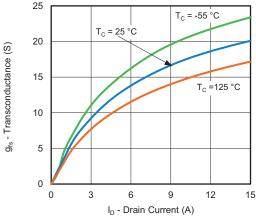
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



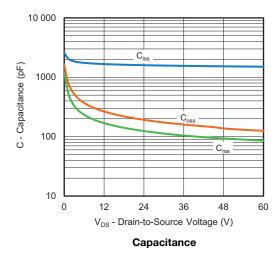
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)

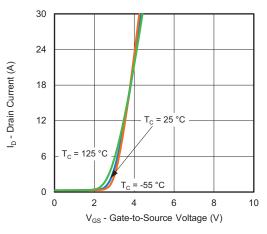


Output Characteristics

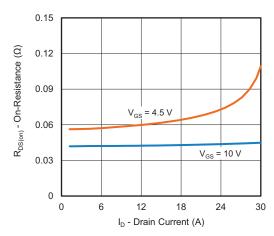


Transconductance

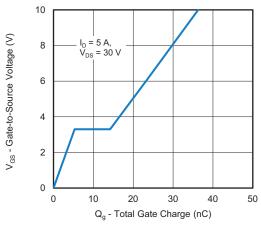




Transfer Characteristics



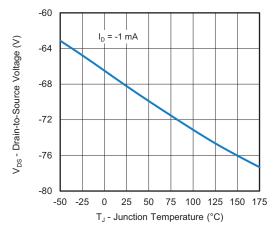
On-Resistance vs. Drain Current



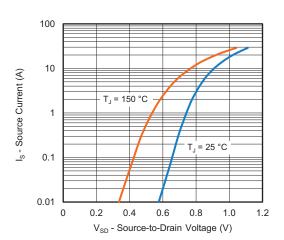
Gate Charge



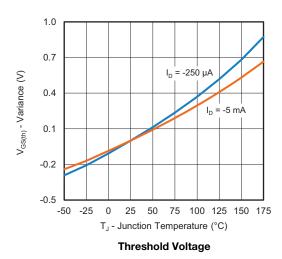
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)

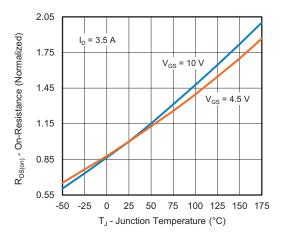


Drain Source Breakdown vs. Junction Temperature

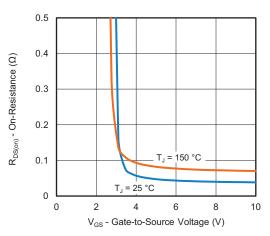


Source Drain Diode Forward Voltage

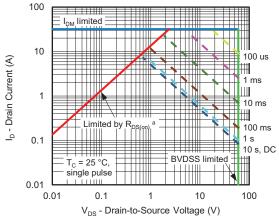




On-Resistance vs. Junction Temperature



On-Resistance vs. Gate-to-Source Voltage



Safe Operating Area

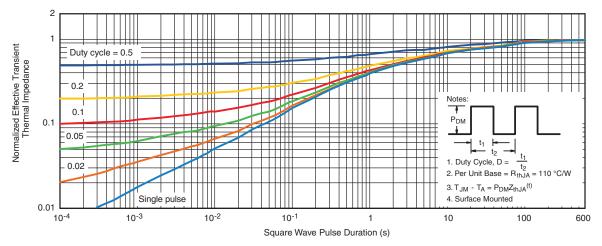
Note

a. V_{GS} > minimum V_{GS} at which R_{DS(on)} is specified

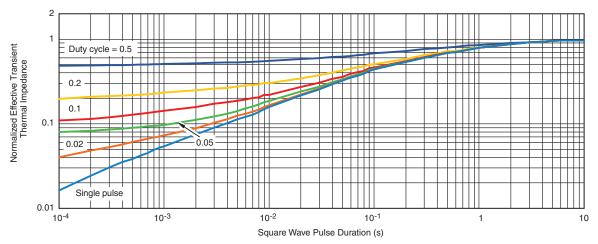
For technical questions, contact: automostech



THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

Note

- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient (25 $^{\circ}\text{C})$
 - Normalized Transient Thermal Impedance Junction-to-Foot (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?62019.



SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012







	MILLIM	IETERS	INCHES		
DIM	Min	Max	Min	Max	
Α	1.35	1.75	0.053	0.069	
A ₁	0.10	0.20	0.004	0.008	
В	0.35	0.51	0.014	0.020	
С	0.19	0.25	0.0075	0.010	
D	4.80	5.00	0.189	0.196	
Е	3.80	4.00	0.150	0.157	
е	1.27	BSC	0.050 BSC		
Н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.020	
L	0.50	0.93	0.020	0.037	
q	0°	8°	0°	8°	
S	0.44	0.64	0.018	0.026	
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RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)

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